Panasonic DB2L33400L1

Schottky Barrier Diode DB2L33400L1

For rectification

Features

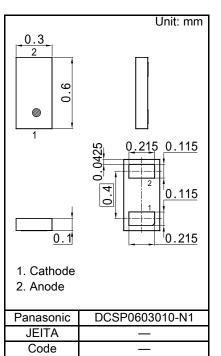
- Average Forward Current IF(AV) ≤ 0.5 A rectification is possible
- Low Forward Voltage
- High power capability due to Chip Size Package RoHS compliant (EU RoHS / MSL:Level 1 compliant)
- Marking Symbol: C5

Packaging

Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Reverse Voltage *1	VR	-	30	V
Maximum Peak Reverse Voltage *1	VRM	-	30	V
Average Forward Current *2,3	IF(AV)	-	0.5	А
Average Forward Current *2,4	IF(AV)	-	0.5	А
Non-repetitive Peak Surge Forward Current *1,5	IFSM	-	5	А
Operating Junction Temperature *6	Tj	-	150	°C
Ambient Temperature	Та	-40	+150	°C
Storage Temperature	Tstg	-55	+150	°C



Note) *1: Ta = Tj = 25°C

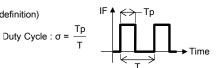
*2: Squre wave : $\sigma = 0.5$

*3: Ta ≤ 82°C, when device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108mm² area, 36µm thick).

*4: Tsp ≦ 138°C

- *5: Squre wave : Tp = 5 ms
- *6: Power derating is necessary so that Tj < 150°C.

(Waveform definition)



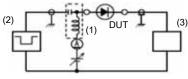
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward Voltage	VF	IF = 0.5 A	-	0.45	0.54	V
Reverse Current	IR	VR = 30 V	-	10	45	μA
Terminal Capacitance	Ct	VR = 10 V, f = 1 MHz	-	10	-	pF
Reverse Recovery Time ^{*1}	trr	IF = IR = 100 mA, Irr = 10 mA	-	3.5	-	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.).

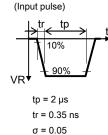
Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment. 3. *1: Measurement circuit, input pulse, output pulse for Reverse recovery time

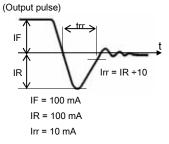
(Measurement circuit)





- (2) Pulse Generator (PG-10N), RS = 50 Ω
- (3) Wave Form Analyzer (SAS-8130), Ri = 50 Ω

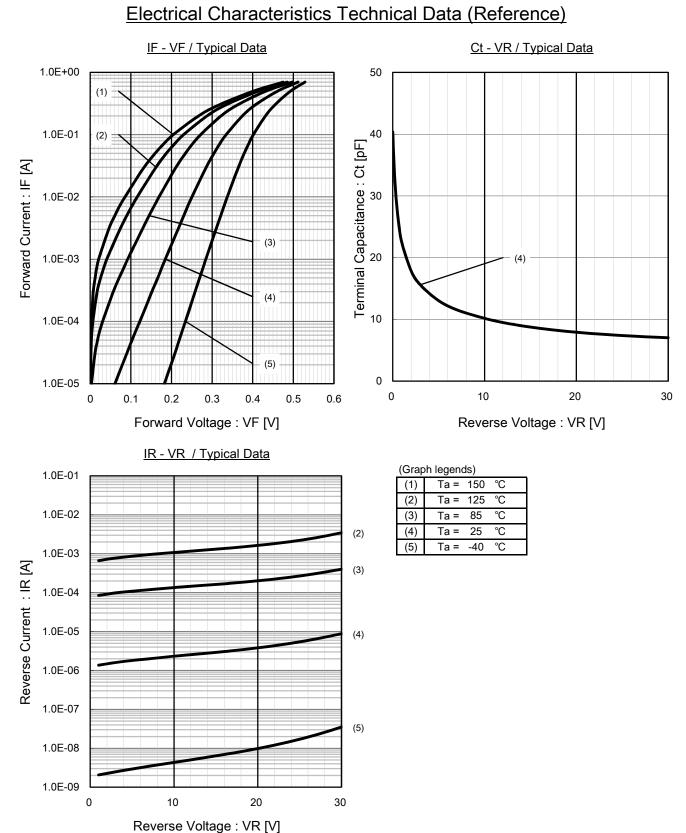




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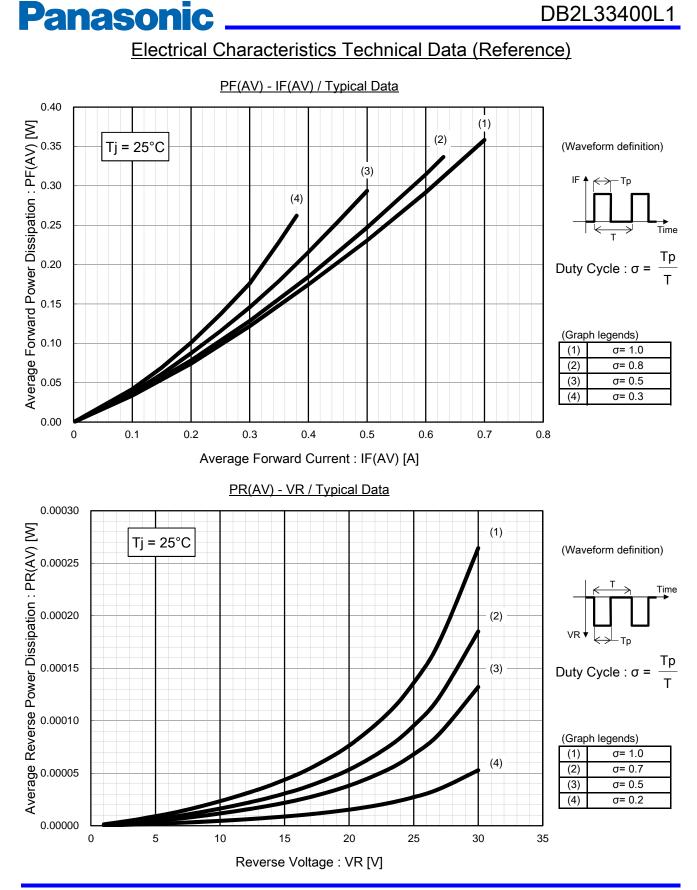


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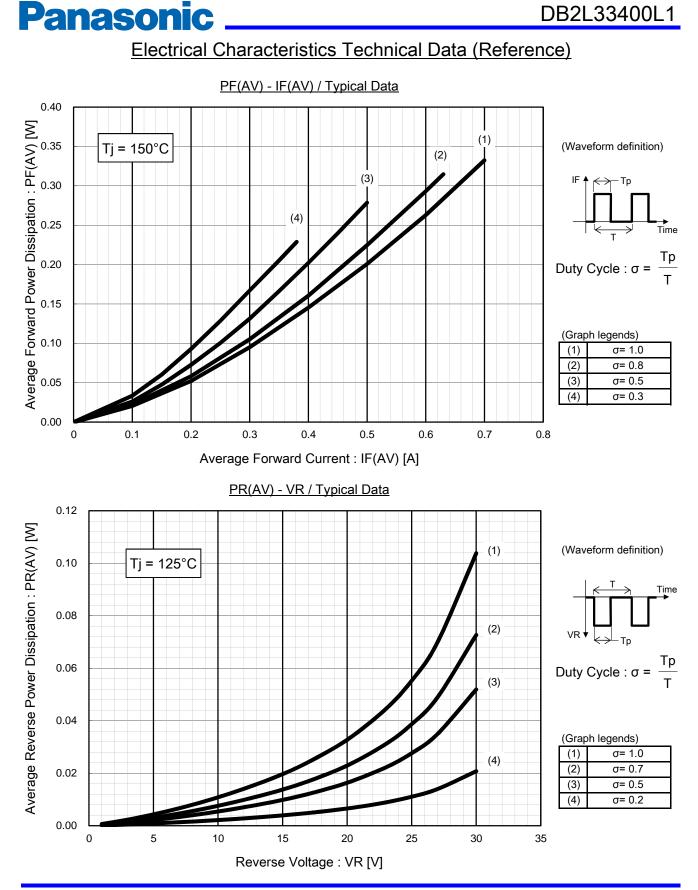


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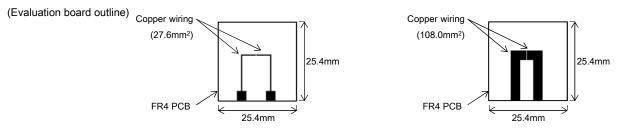
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Thermal Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Thermal Resistance, Junction to Solder Point	$R_{th(j-sp)}$	Ta = 25°C, in free air	-	35	-	°C/W
Thermal Resistance, Junction to Ambient ¹	R _{th(j-a)}	Ta = 25°C, in free air	-	610	-	°C/W
Thermal Resistance, Junction to Ambient ^{*2}	R _{th(j-a)}	Ta = 25°C, in free air	-	202	-	°C/W

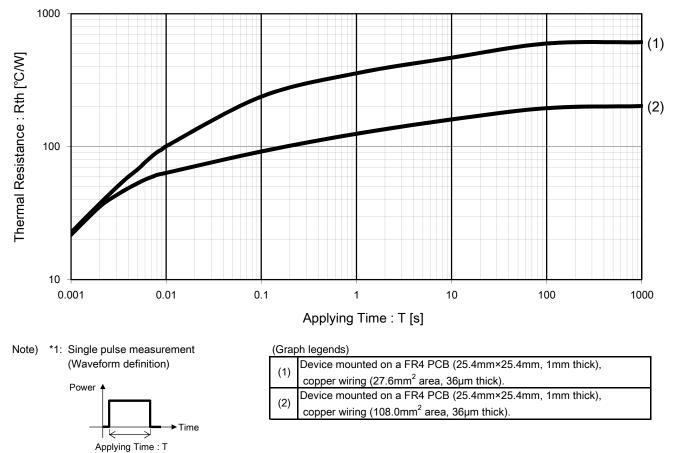
Note) *1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (27.6mm² area, 36µm thick).

*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.0mm² area, 36µm thick).



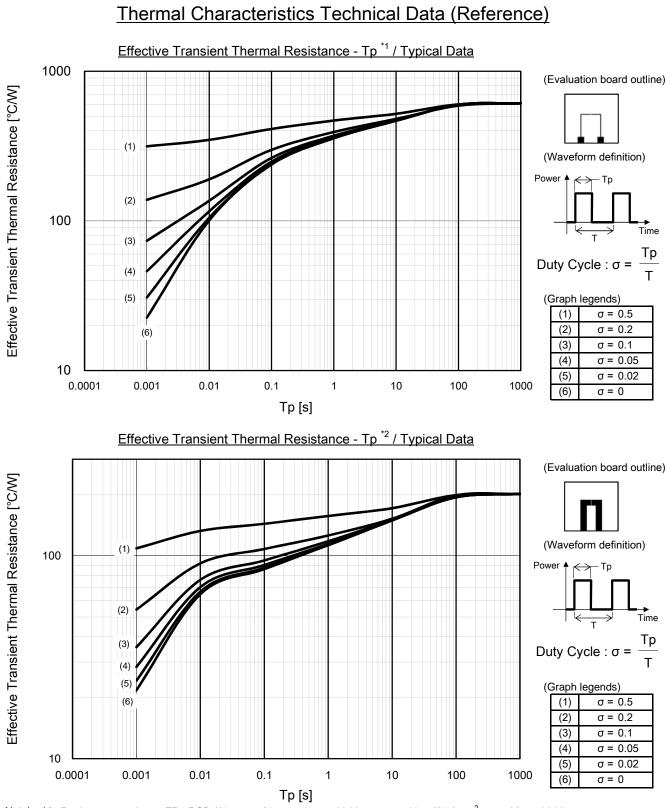
Thermal Characteristics Technical Data (Reference)

Rth - T *1 / Typical Data



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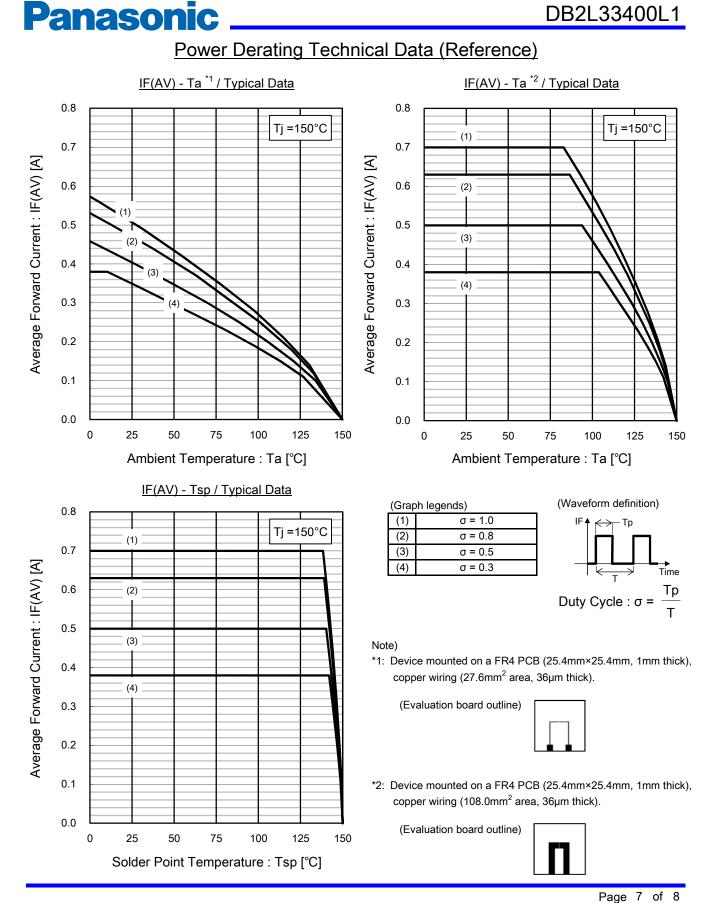
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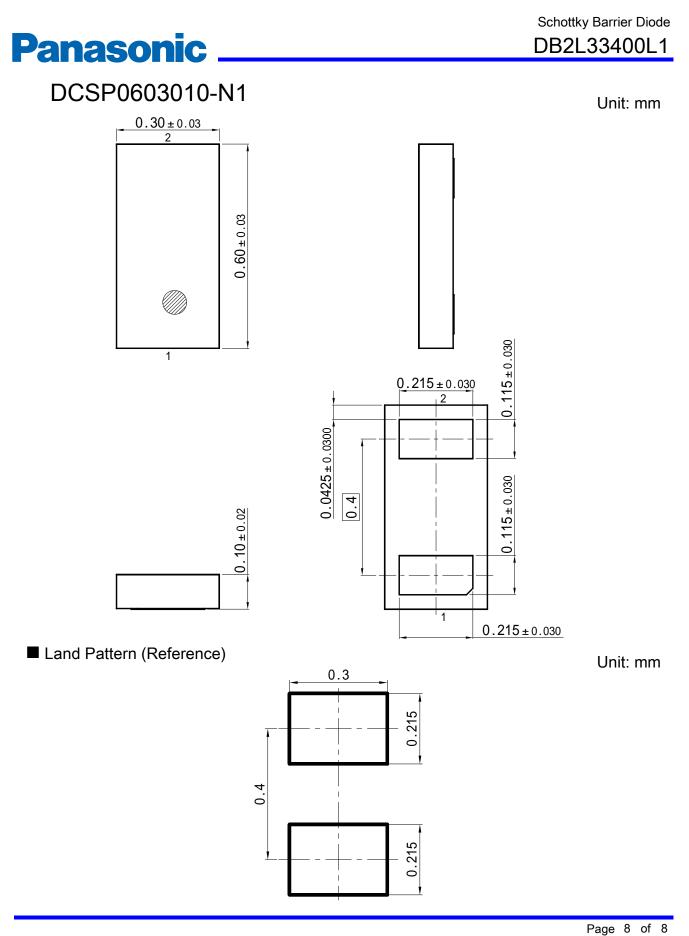
Note) *1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (27.6mm² area, 36µm thick).
*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.0mm² area, 36µm thick).

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